

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. MASUDA, et al

#16 DATE
2/20/02
MU

Serial No.: 09/421,043

Filed: October 20, 1999

For: PLASMA ETCHING APPARATUS AND PLASMA ETCHING
METHOD

Group: 1763

Examiner: A. Mulero

DO NOT
ENTER
SIAA
02/21/02

AMENDMENT AFTER FINAL ACTION

Commissioner for Patents
Box AF
Washington, D.C. 20231

February 19, 2002

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated October 23, 2001.

IN THE SPECIFICATION:

Page 21, please amend the paragraph beginning at line 12 as follows:

Firstly, the side wall 102 will be explained by referring to Fig. 1. As already explained, the jacket 103 is held inside the side wall 102 of the processing chamber 100 and the temperature can be controlled by a heat exchanging medium.